

# The role of Si tracking components in the LDC concept

Aurore Savoy-Navarro, LPNHE-Universités de Paris 6&7/IN2P3-CNRS  
[aurore@lpnhep.in2p3.fr](mailto:aurore@lpnhep.in2p3.fr) [aurore.savoy@cern.ch](mailto:aurore.savoy@cern.ch)

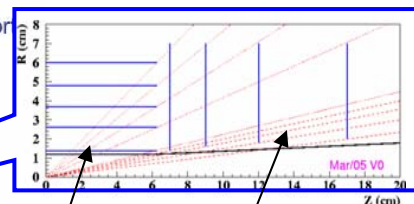
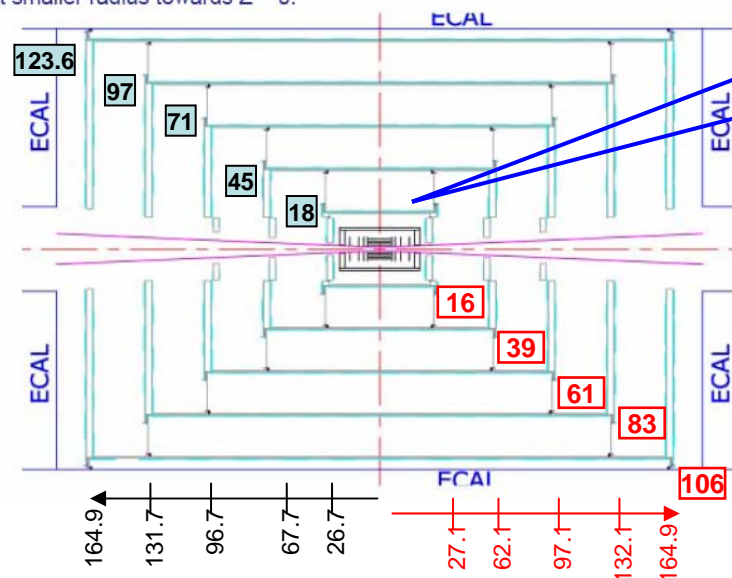
*The work reported here is ongoing in the framework of the SiLC (Silicon tracking for the Linear Collider) R&D collaboration*

**2005 ALCPG Meeting in Snowmass,  
14th to 27th August 2005  
LDC Concept Working Session 8/16/2005**

- What are the various possible Si tracking components in the LDC-like concept
- Their role, their design, their performances, their main issues
  - Where do we stand?
- What can we achieve during this workshop?

# The concepts: main difference = tracking strategy

The outer silicon tracker has been separated into a portion supported from the ECAL and a portion supported from the beam pipe to allow servicing of the VXD. Overlap between smaller and larger disk portions is provided by offsetting the portion at smaller radius towards Z = 0.



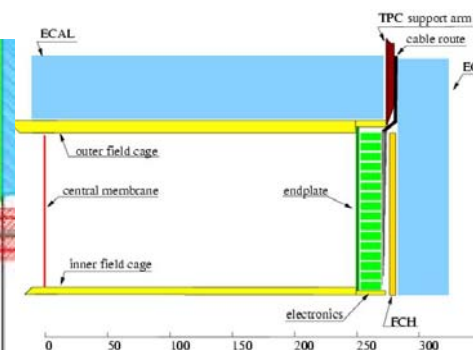
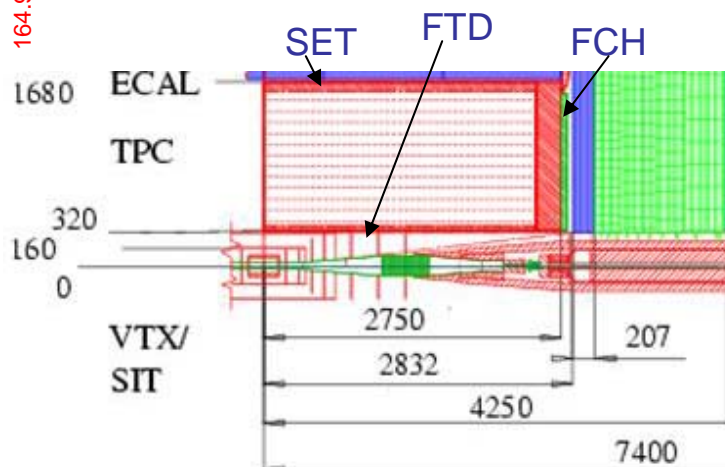
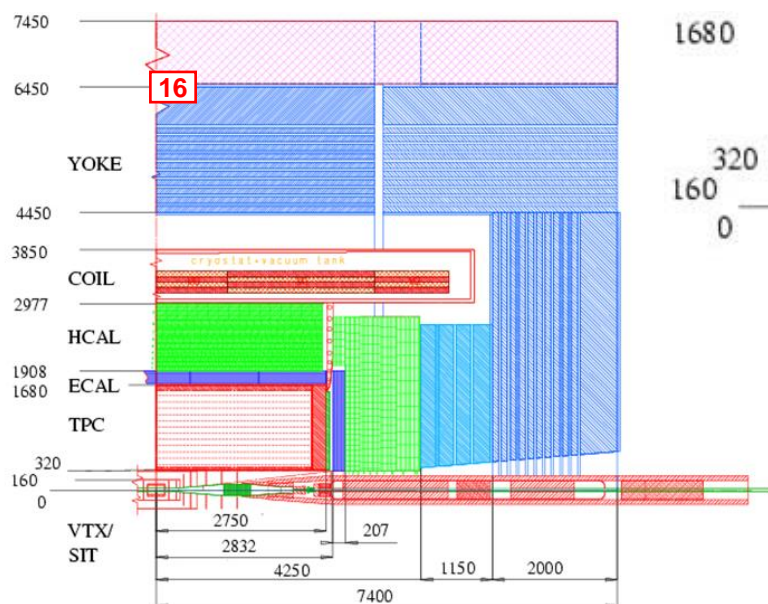
VXD

4 disks  
Z(cm)=7, 9.9, 12, 17  
Rmin=1.4, 1.6, 1.8, 2  
Max Radius~7cm

## SiD Concept

### SiD tracking in numbers

Barrel: 5 layers S.S (Phi)  
(up to 10 layers under consideration)  
Rmin:18.6cm Rmax: 123.6cm  
Zmin=26.7cm Zmax=164.9cm  
Endcaps: 5 layers F.D.S.  
(back to back double layer stereo)  
Zmin=27.1cm Zmax=164.9cm  
If 5 layers:  
Overall surface ~100m<sup>2</sup>  
Number of channels ~16M.



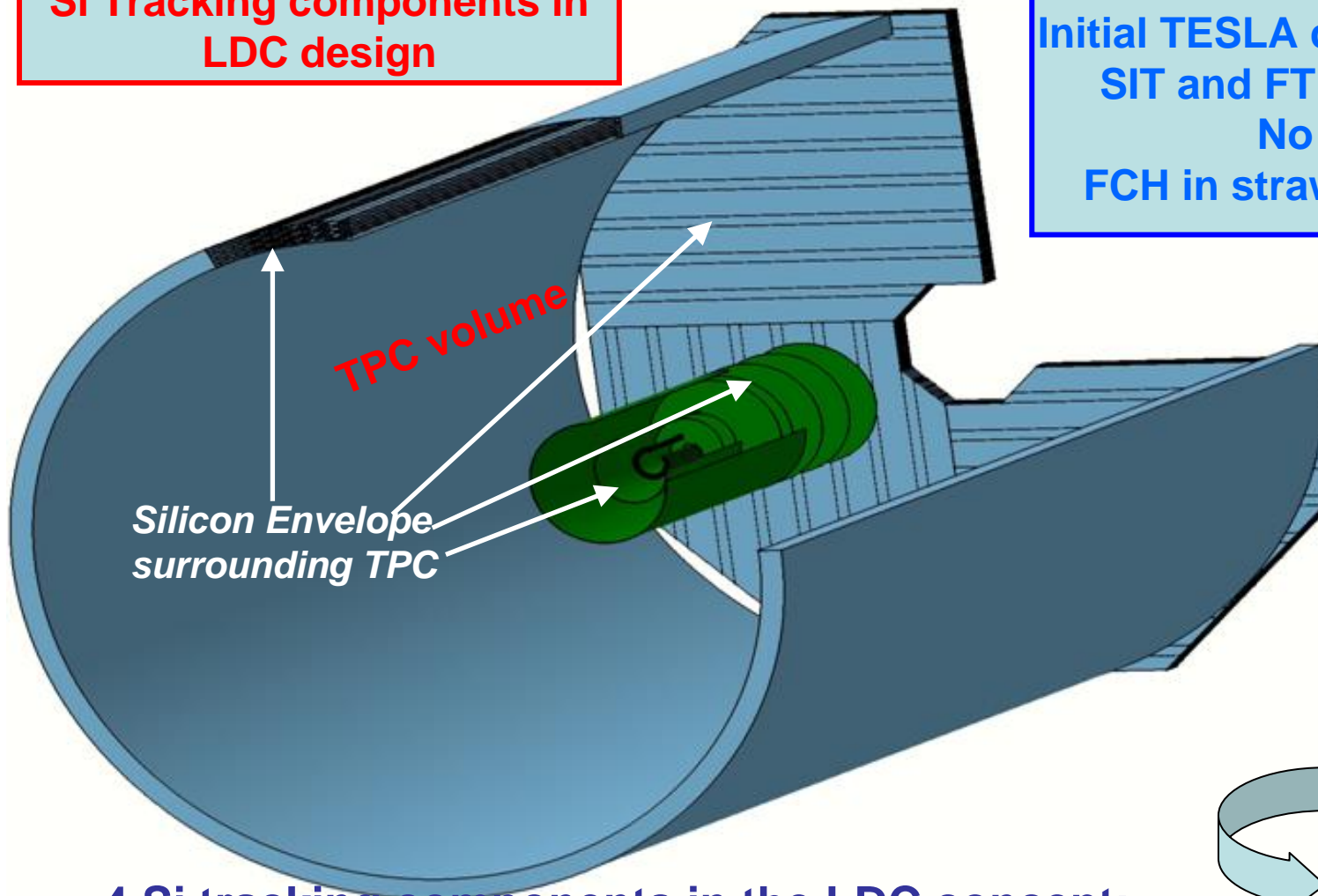
## LDC Concept

### LDC trackers in numbers:

Barrel=TPC +SIT +SET, Rmin=16cm Rmax=168cm  
Endcap=FTD+FCH, Zmin=16cm, Zmax=275cm  
Overall Si-surface (Si envelope)~200m<sup>2</sup> x 2, Nb of ch~4-6M

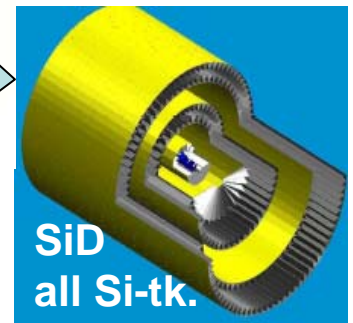
**Si Tracking components in LDC design**

**Initial TESLA detector design:**  
SIT and FTD (Si techno)  
No SET  
FCH in straw tube techno



**4 Si tracking components in the LDC concept:**  
internal and external Si tracking components  
in  
barrel and large angle (forward/end caps) regions  
acting as intermediate trackers  
and forming a complete coverage Si tracking system

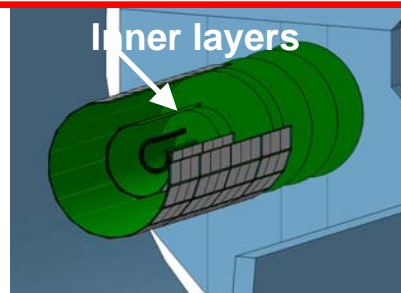
**How it compares with SiD tracker?**



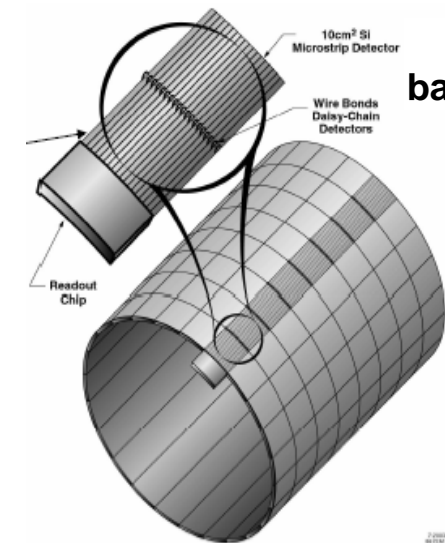
Design, role, performances  
& main issues:

Where do we stand  
component by component

# The central barrel

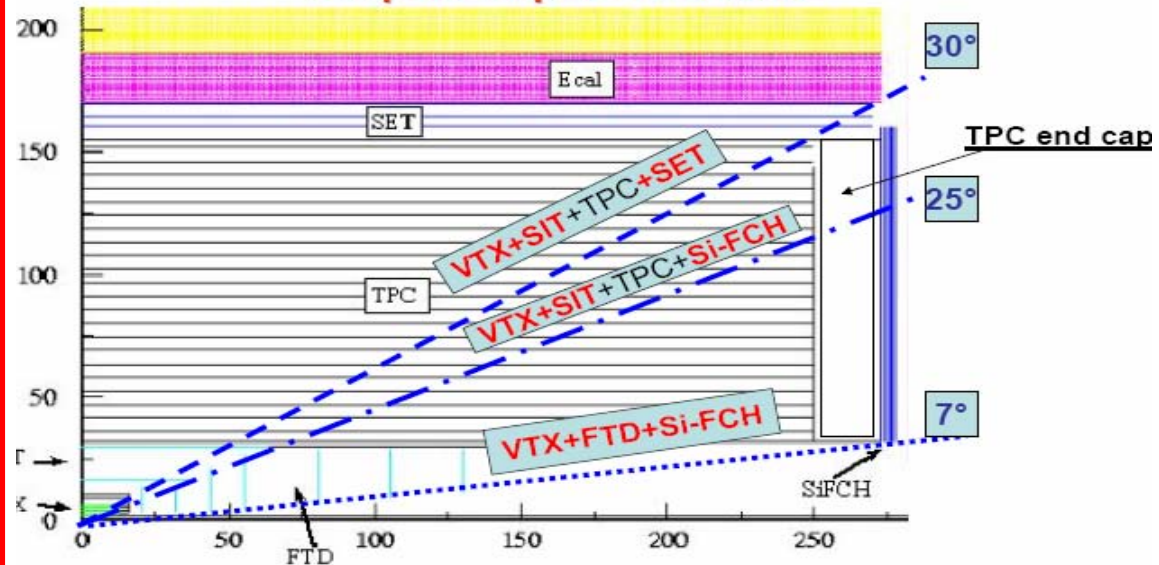


Link  $\mu$ vertex  
to larger area  
external layers  
( $7\mu$  precision)



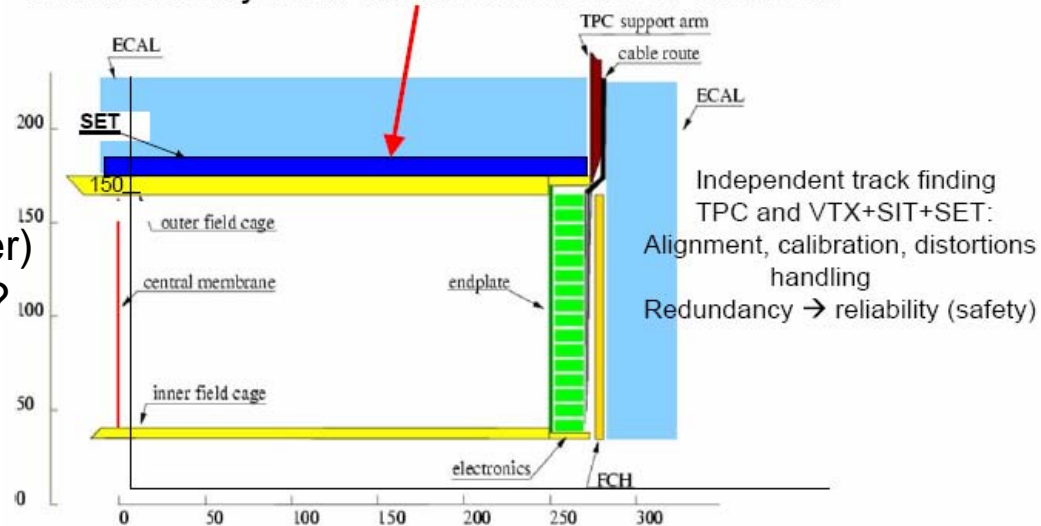
External  
barrel layers

- ✓ Robustness
- ✓ Full coverage
- ✓ Improved performances



If a TPC: SET (Silicon External Tracker) proposed in LC-DET-2001-075.  
Located between TPC and e.m. calorimeter

Optimized with 3 layers, two single sided external layers, one d.s.  
intermediate layer and overall structure based on alveoli.



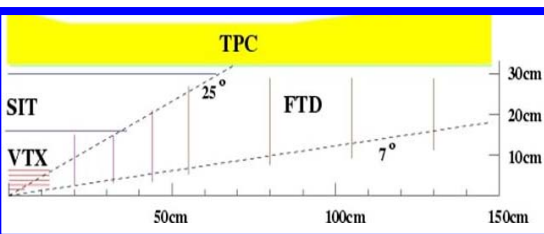
## Questions:

- Tiling or not tiling? (medium size ladder)
- How many layers? DS (FDS) or not?
- Structure with alveoli?
- Large area support structure vs low material budget
- Metrology, alignment

# The internal forward Si component

see Klaus' talk for physics motivation and initial design

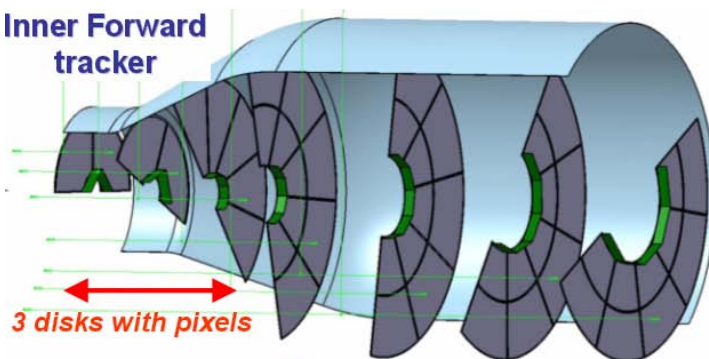
N.B. It is made of 2 parts:  
the first 3 or 4 disks  
(forward extension of  $\mu$ vertex)  
and the remaining ones



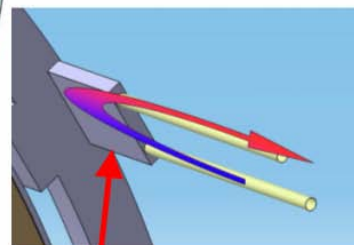
The TPC doesn't help at large angle  
The FTD will be the first part of the  
overall L.A.R. tracking system,  
completed by the Si-FCH  
(Standalone Si system)

Envelope for isolating  
and cooling

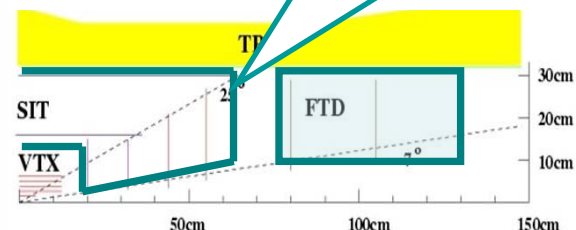
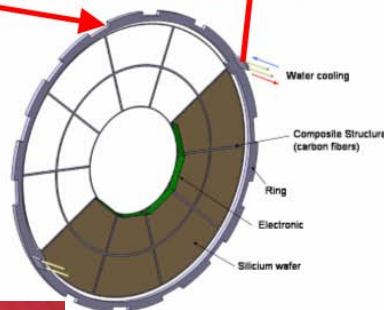
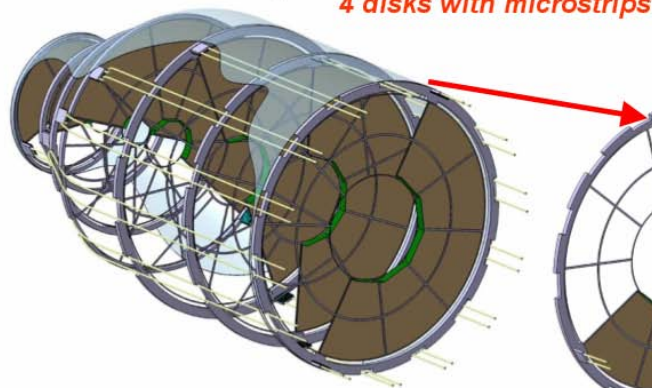
Inner Forward  
tracker



Cooling under study:  
based on water cooling  
with water  $T < 10^\circ\text{C}$ , flowing  
through the rings  
(to be checked on  
mechanical prototype)



4 disks with microstrips

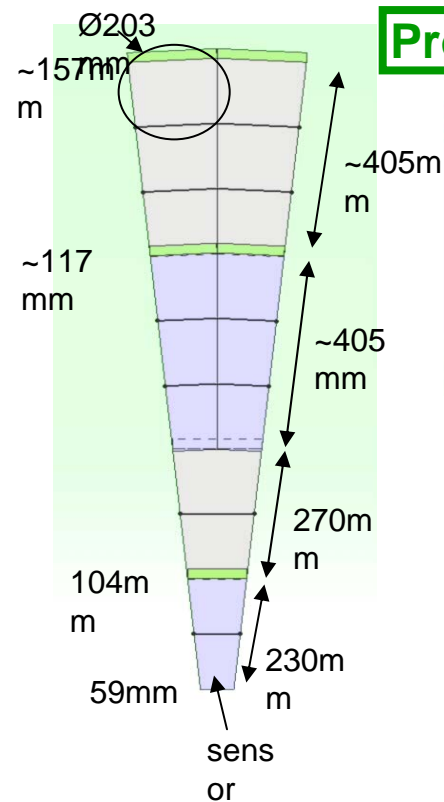


The cooling in this strategic  
place is trickier. The design  
of a realistic prototype to study  
this problem is underway.

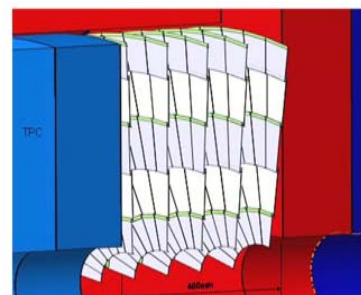
*Nota Bene: the first disks of the inner  
Forward Si tracker could/should be  
equipped with sensor techno as  
those developed for the  $\mu$ vertex.  
The VELO sensors of LHCb, could  
be of interest for some case as well  
(under investigation)*

# The Endcap Si components

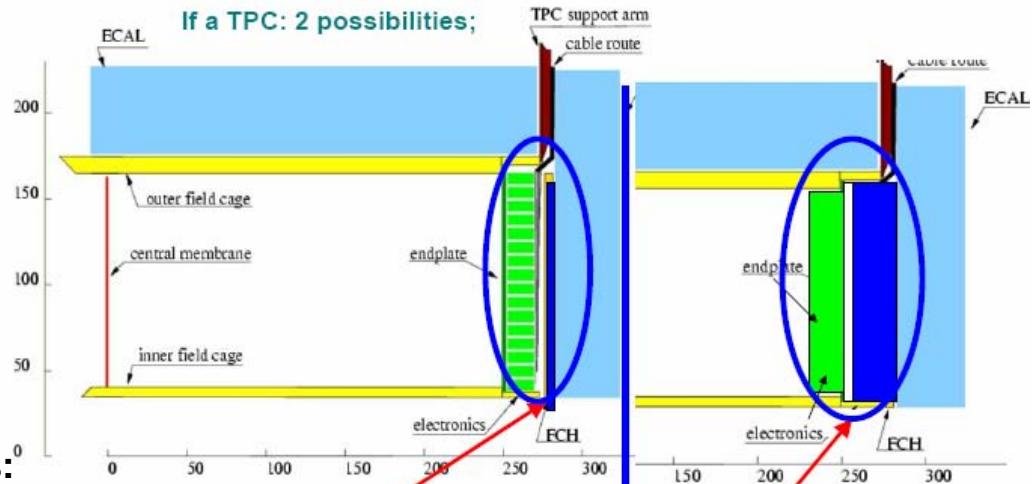
Endcap components both internal and external are essential: Physics @  $E_{cm}=1$  TeV is demanding highly performing tracking at large angles. Lot of work going on



**Projective**



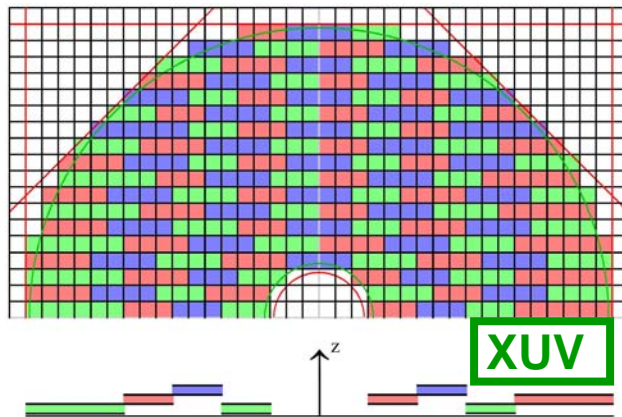
**LDC design:**  
**5 F.D.S stereo planes:**  
**10240 sensors**  
**3840 modules**  
**2 to 4M channels**



The external forward Si-tracker is compressed between TPC endplate and the calorimetry. Thus it is more a linker than a real tracker.

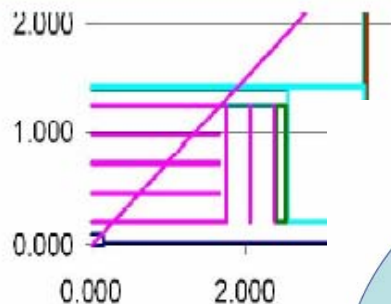
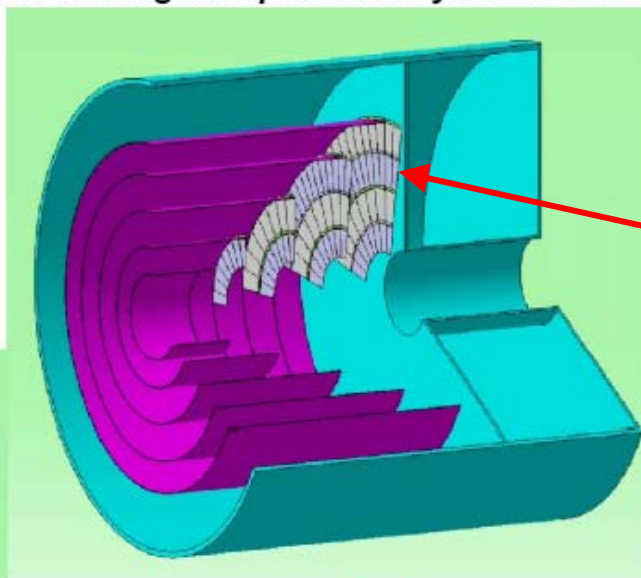
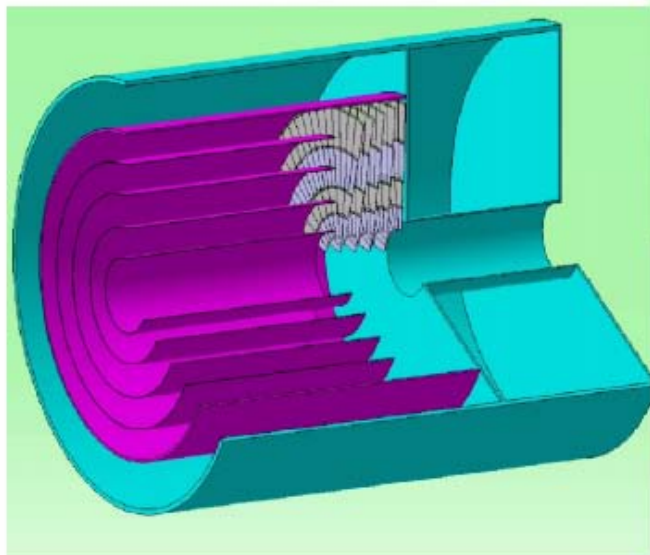
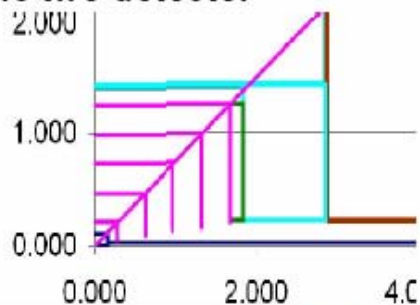
The external Si-tracker is extended over about 40 cm thus it provides real tracking (level-arm) (this means a shorter TPC)

*Simulation studies needed !!*



The XUV design is being revisited. No more structure with alveoli. Advantage of the XUV: use only one **single type of sensor**: here 10x10 cm<sup>2</sup> that can be arranged in modules of 3, 4 and 6 sensors. This also fits easily with an octagonal overall support structure

How it compares with the SiD Forward tracking ? Important key issue to evaluate the two detector concepts

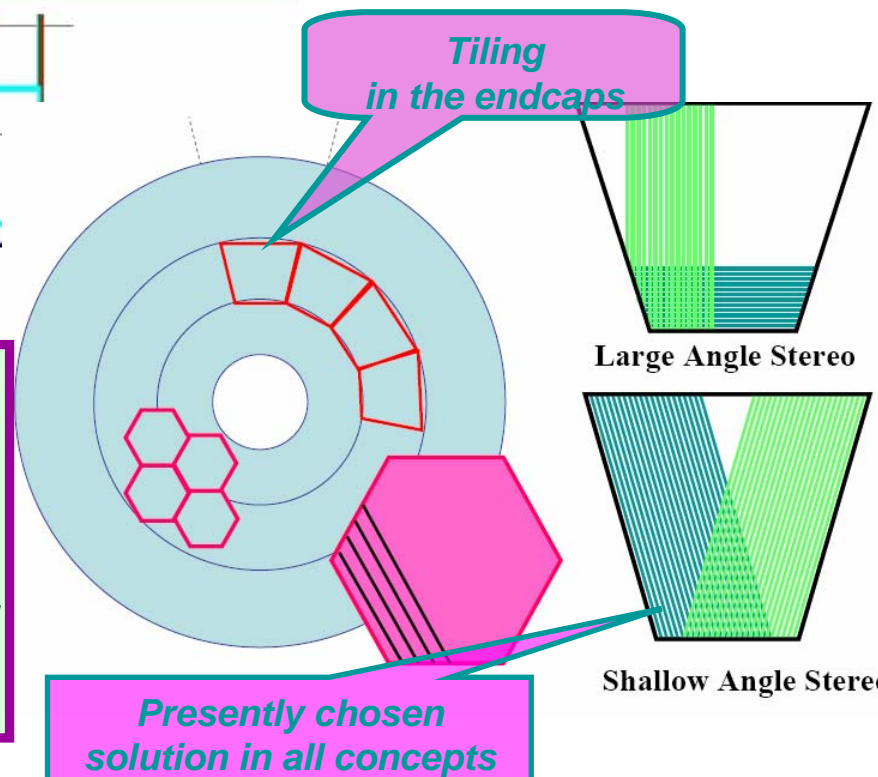


## Endcaps in the SiD concept

The designs in previous slide are directly applicable to SiD as well as to GLD.

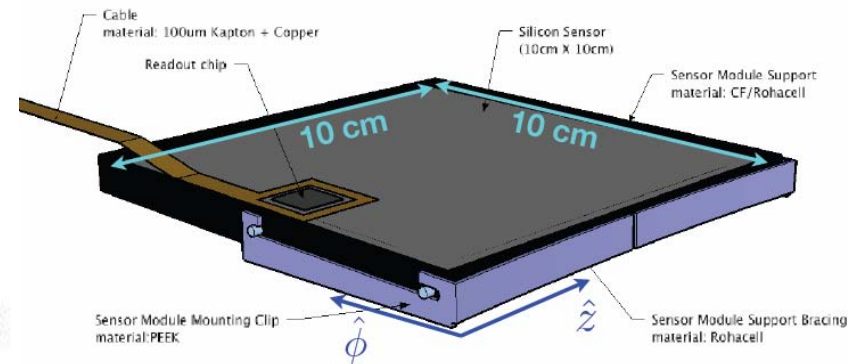
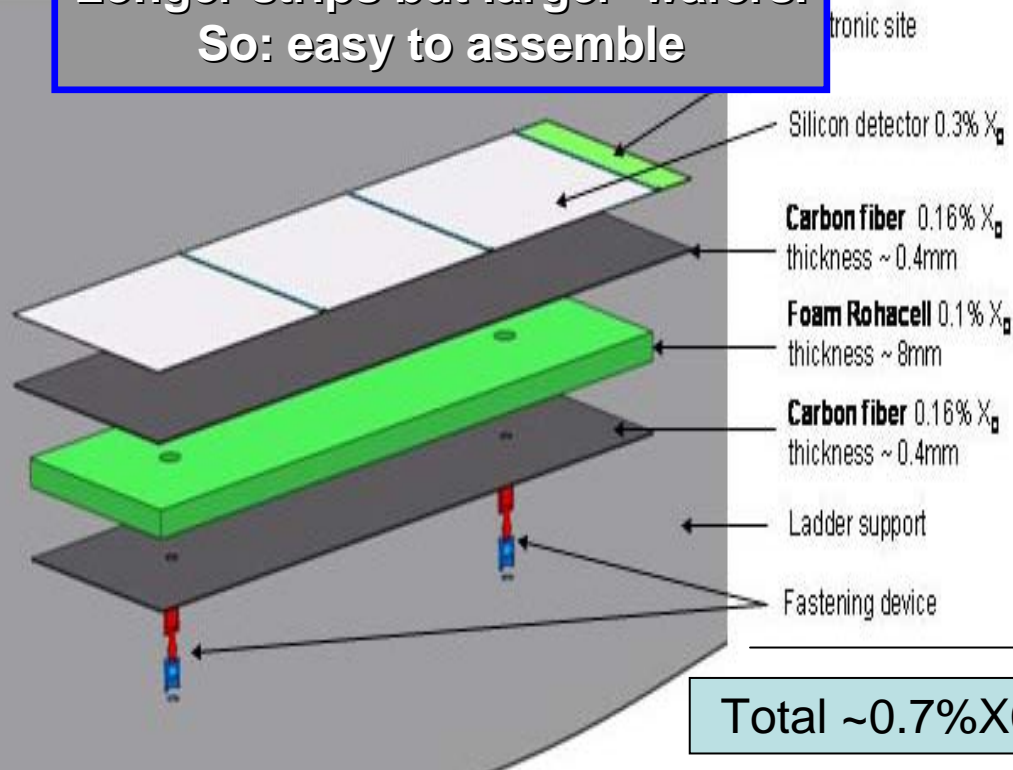
The projective design is currently favoured for SiD. But XUV is also under study.

- Two remarks valid for all detector concepts:**
- 1) Performances at large angle will be a decisive parameter when comparing with or without TPC tracking systems
  - 2) Optimisation of the overlap between central and endcap parts: key issue wrt material budget



# Elementary modules (revisiting existing techniques)

Longer strips but larger wafers.  
So: easy to assemble

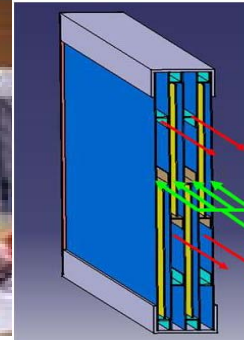


## Key issues:

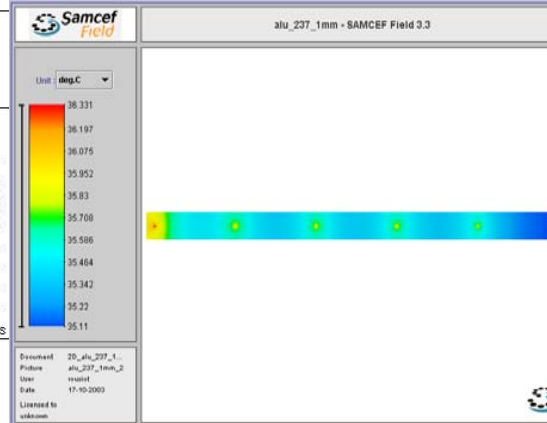
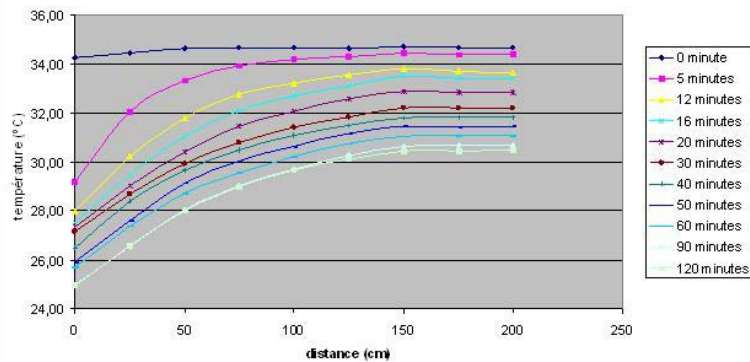
- **Minimum material Budget**
- **Best strips alignment**
- **Most accurate positioning of the module on the support structure (large size!)**
- **FE electronics connectics, packaging and cabling**
- **Cooling**
- **Easy to build (robotisation ?)**
- **Transfer to Industry (large nb)**
- **Universal tile vs various types**
- Be innovative!**

Occupancy studies tend to confirm that strips of 30 up to 60 cm length are adequate for most of the detector components. Modules with single sensor are also considered in this R&D.

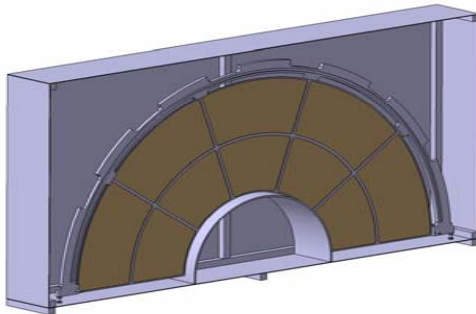
# Thermo mechanical studies



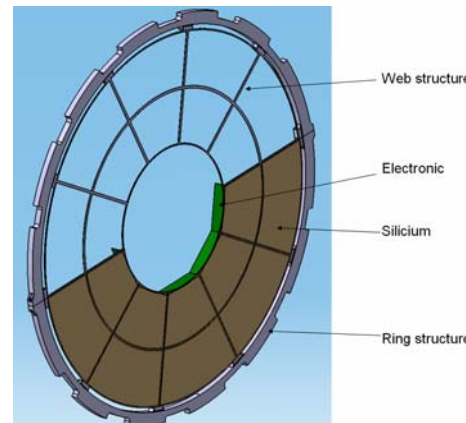
évolution du profil de température au cours du temps



**Extensive studies  
on realistic external  
central & forward  
prototypes gives: air  
conduction + convection  
Is sufficient;  
What really matters  
Is the environmental  
temperature**



**preliminary design of the mechanical  
prototype to test the cooling system  
for a disk of the inner forward**

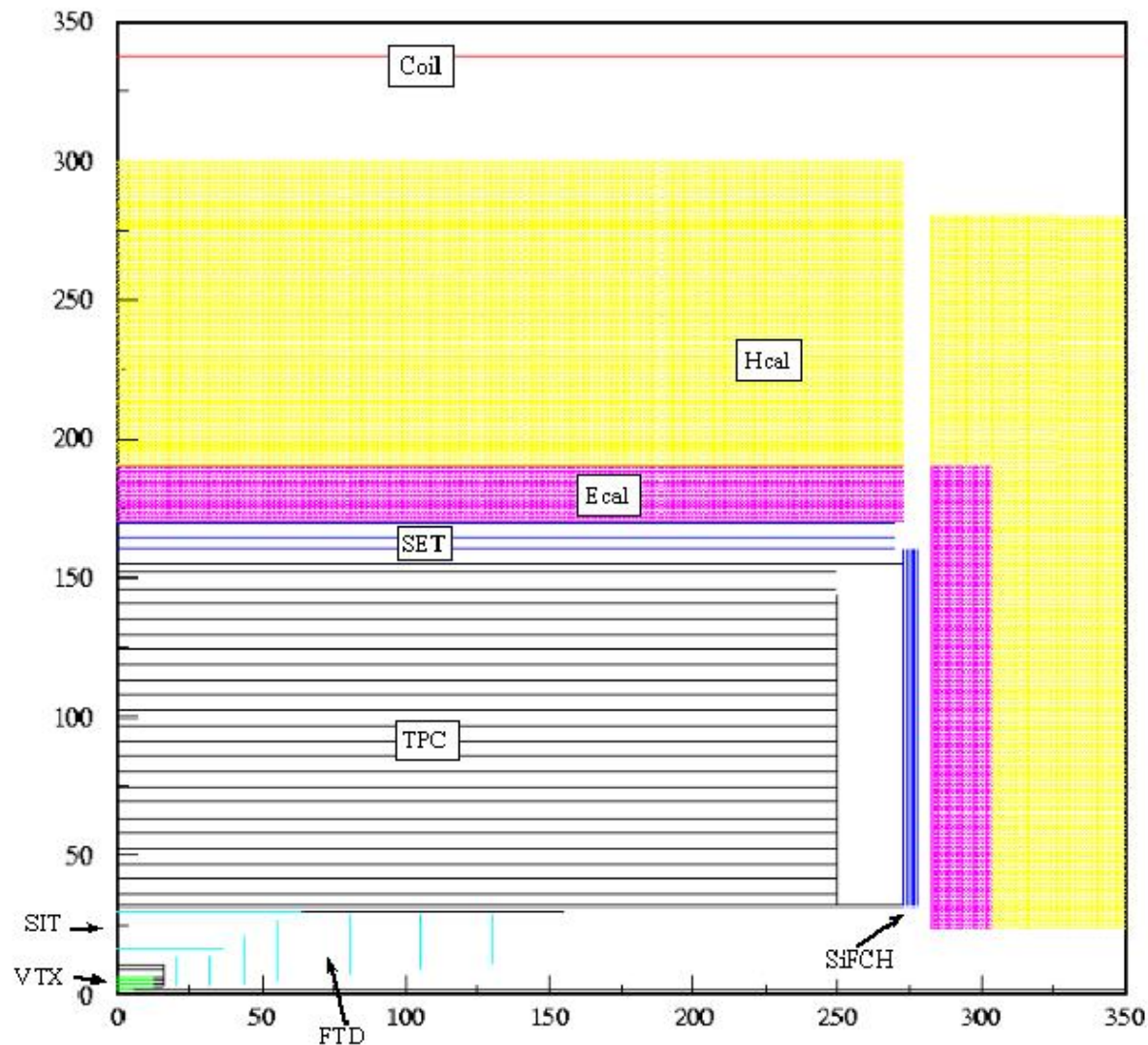


**Now starting,  
cooling studies  
of the inner parts:  
a bit more tricky...**

# Other issues under study

- Alignment **S** (*strips, sensors in elementary module, modules on support structure, support structures in overall detector*)
- Accurate positioning of elementary modules
- Mechanics: low material budget, easiness of construction (simple modular structure, transfer to industry), robustness, full coverage, low cost,
- Integration issues
- Electronics: lot of progress underway based on dsm techno with low noise, low power dissipation, compact, highly multiplexed, high performances.
- Simulation studies:
  - Initial simulation studies on detector performances performed with SGV (fast but detailed enough MC)
  - Now Silicon envelope and SiD geometries defined in GEANT4 DB and also in Brahms

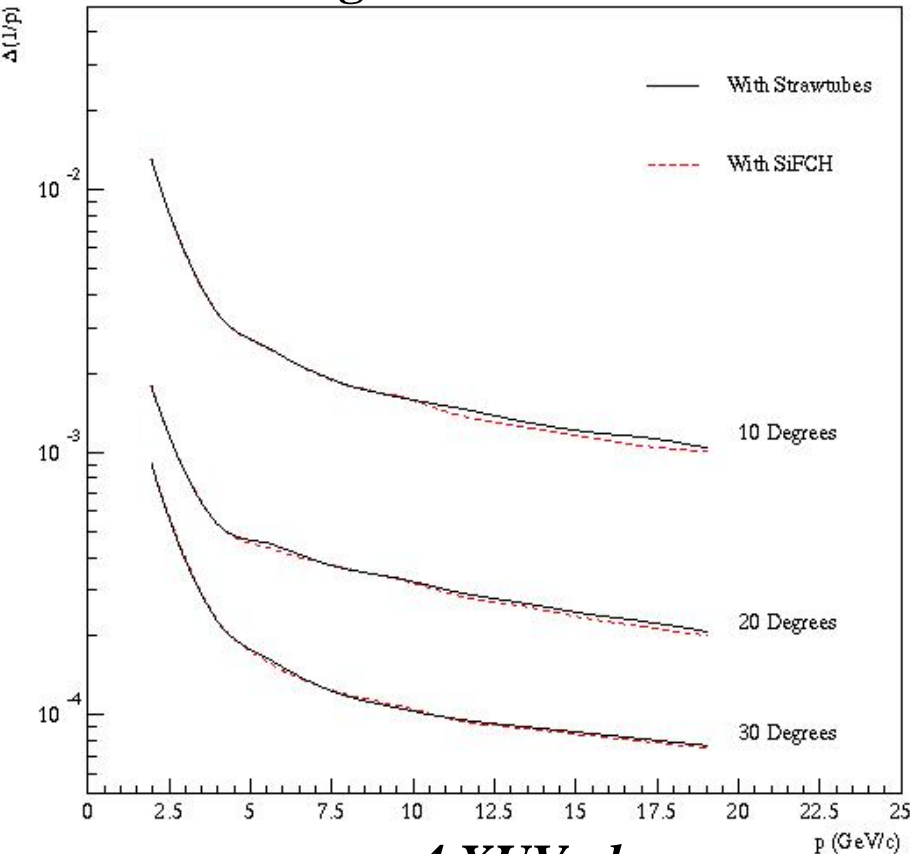
# 1) Simulation studies with SGV



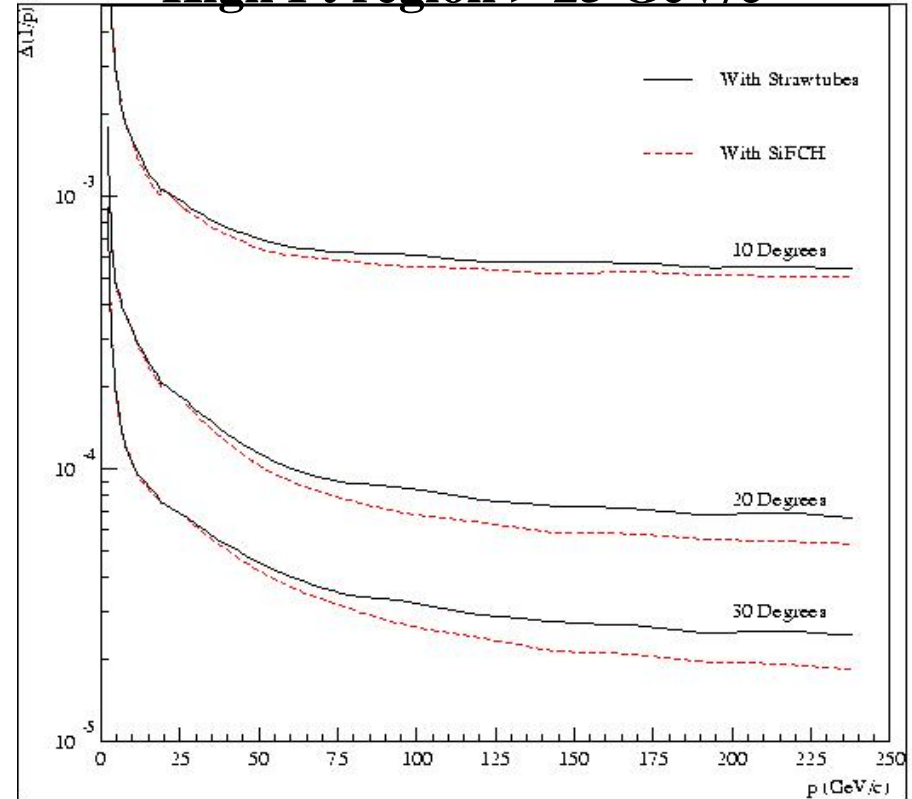
*Although a fast simulation, SGV includes: multiple scattering, materials, spiraling of low momentum charged tracks etc...*

# Si-FCH performance studies with SGV

Low Pt region < 25 GeV/c



High Pt region > 25 GeV/c



*4 XUV planes are considered in TESLA TDR*

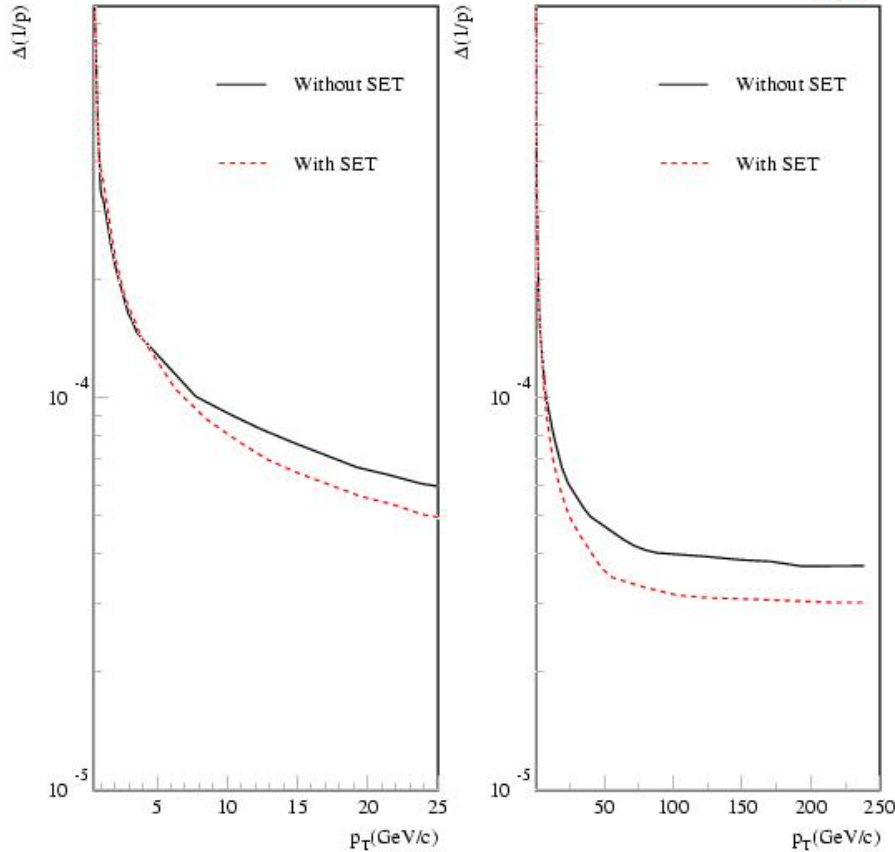
**Momentum resolution if: TPC+straw tubes (100 $\mu$ m res./pt)**

**TPC+Si-FCH (25 $\mu$ m res./pt)**

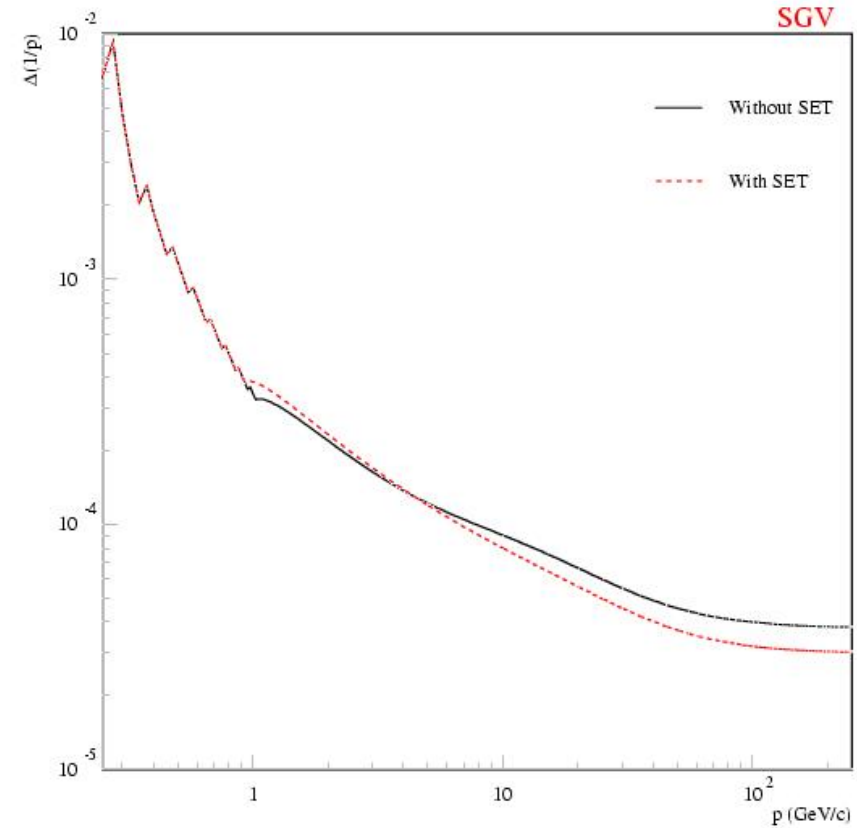
*Si-FCH better than straw tubes for large impulsions and when angle/ beam increases*

**Special & detailed study to be done for the very low angle regions (<10 ° or so)**

SGV



All P range: up to 250 GeV/c



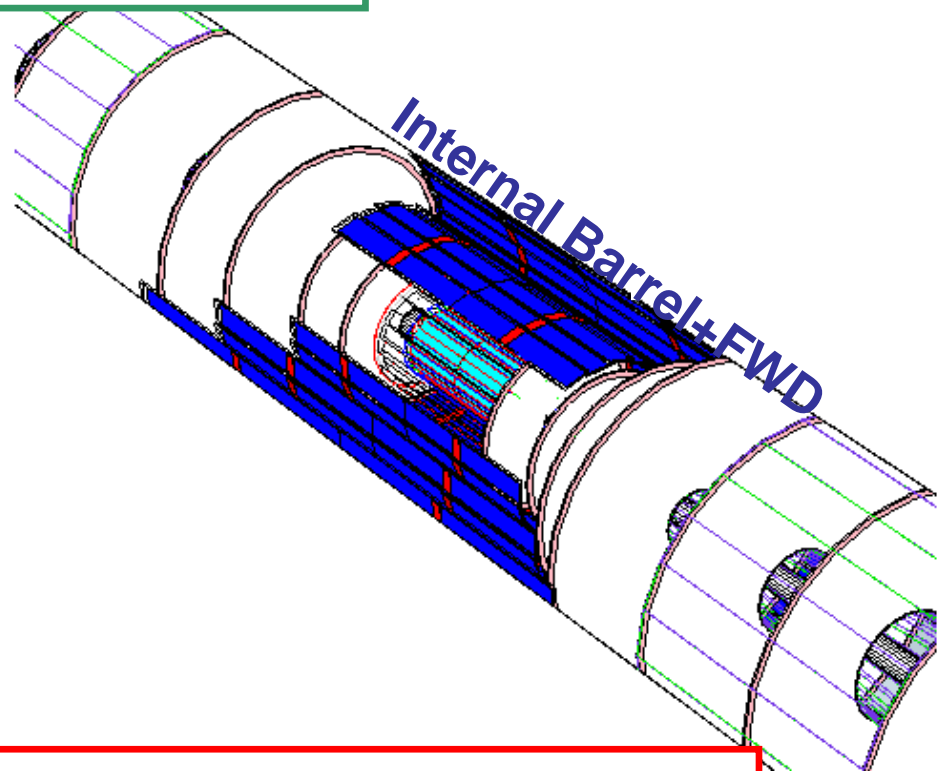
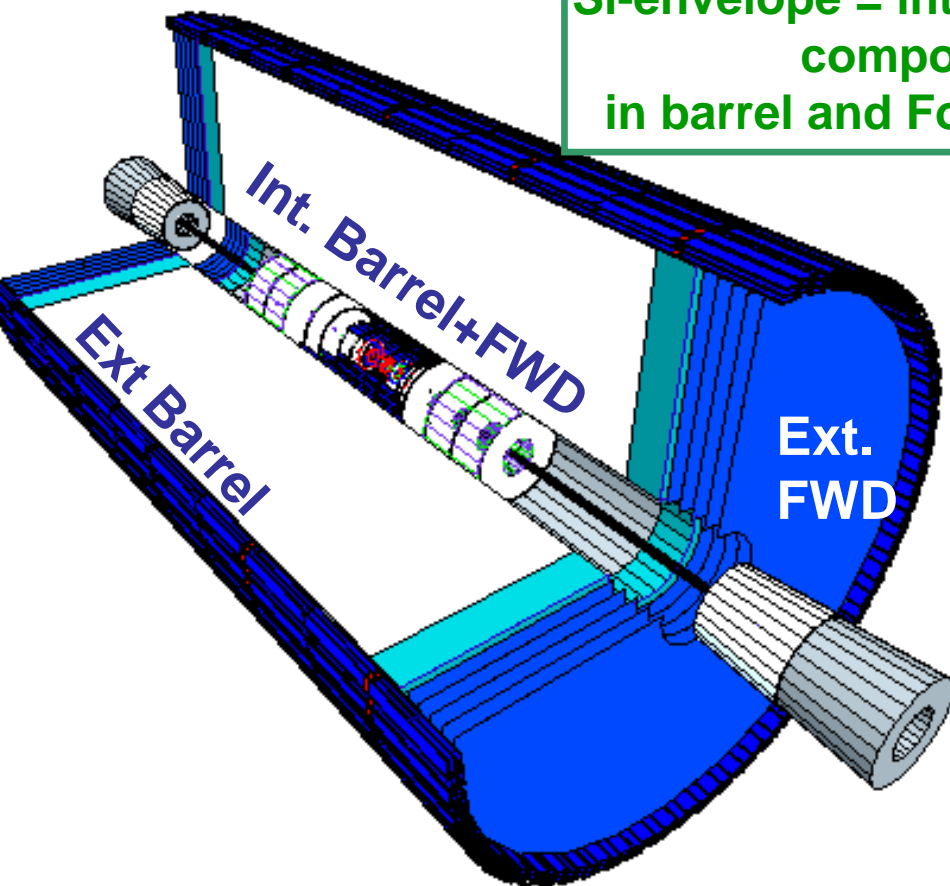
**Assuming:** TPC reduced to 155cm in radius & resolution/pt=100  $\mu\text{m}$ , an improvement up to 15-20% is observed at high momentum and, at low momentum the 2 resolution curves cross at 4.5 and 1 GeV/c ( tracks below 1 GeV/c do not reach the SET)

## 2) Geometry DB for Si tracking systems in G4

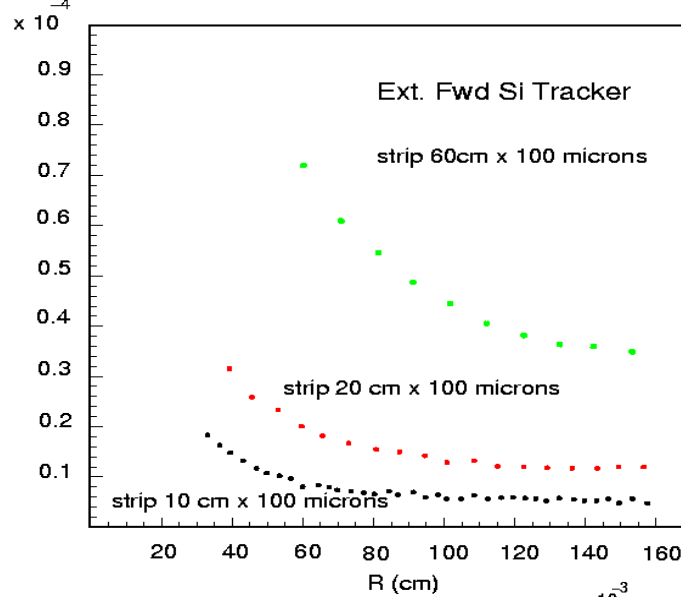
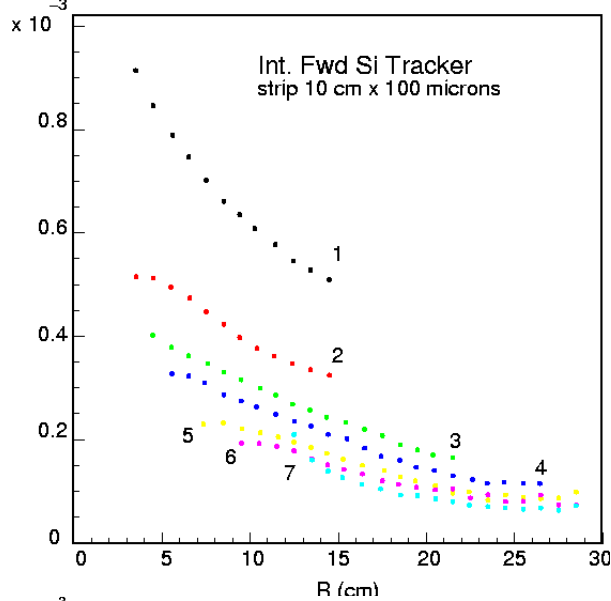
(V. Saveliev, DESY-Obninsk)

***both for the Si Envelope and SiD***

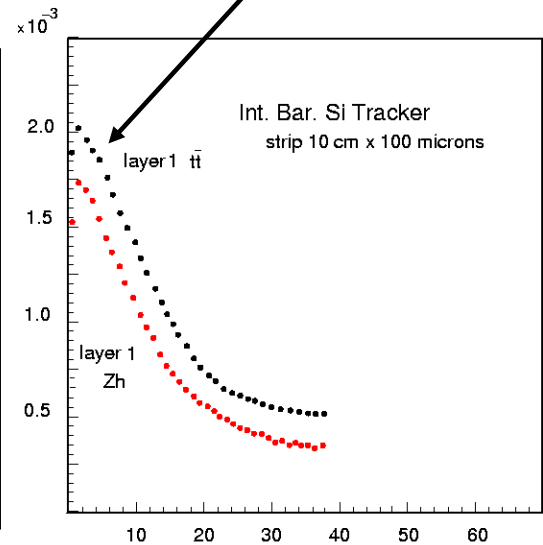
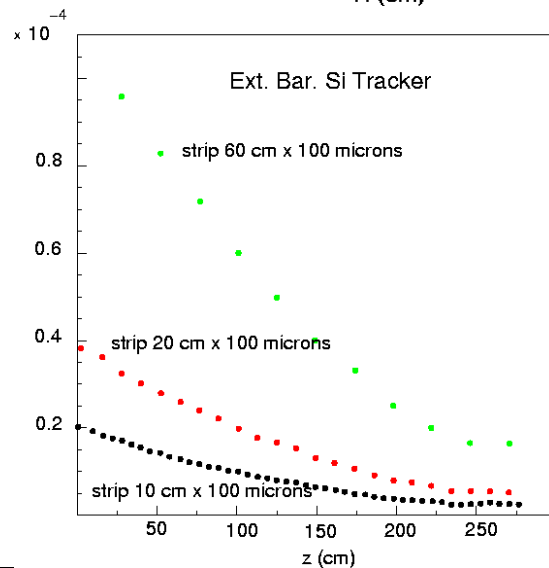
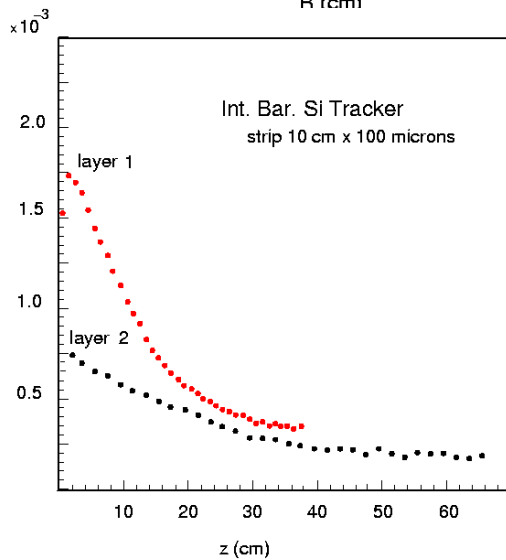
Si-envelope = internal & external  
components  
in barrel and Forward regions



**The DB definiton has been sent to the official DB:**



**$t\bar{t}$ bar/ HZ gives  
~20% higher  
occupancy**

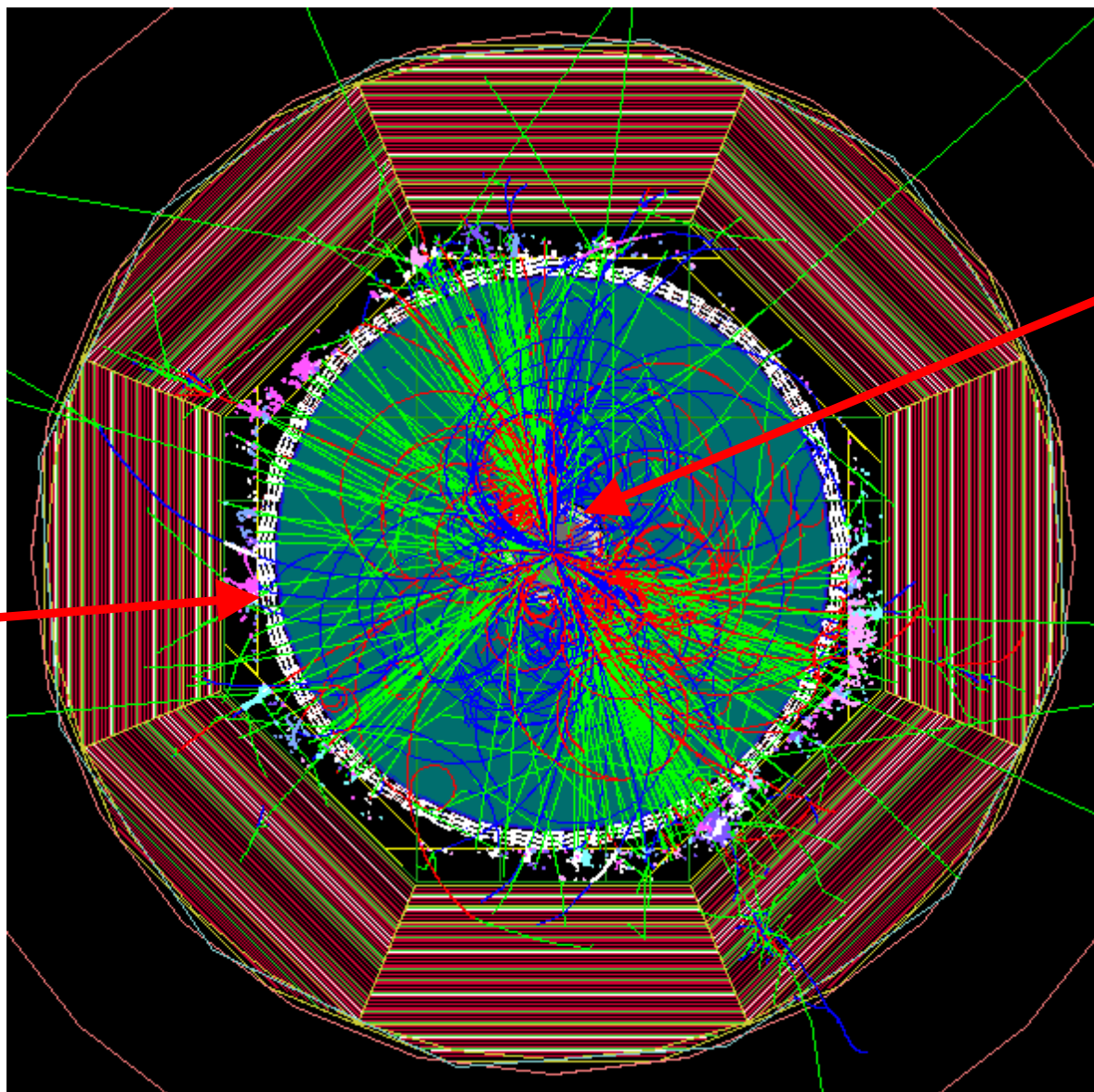


**Occupancies are calculated with BRAHMS full simulation (Si-Envelope+TPC),  
Higgstrahlung HZ with  $b\bar{b}$  and  $q\bar{q}$  at  $E_{cm}=500$  GeV  
Values at most of order 1% to 2% for the hottest places in the detector!**

**Strips of length from 30cm to 60cm are appropriate.**

**LDC**

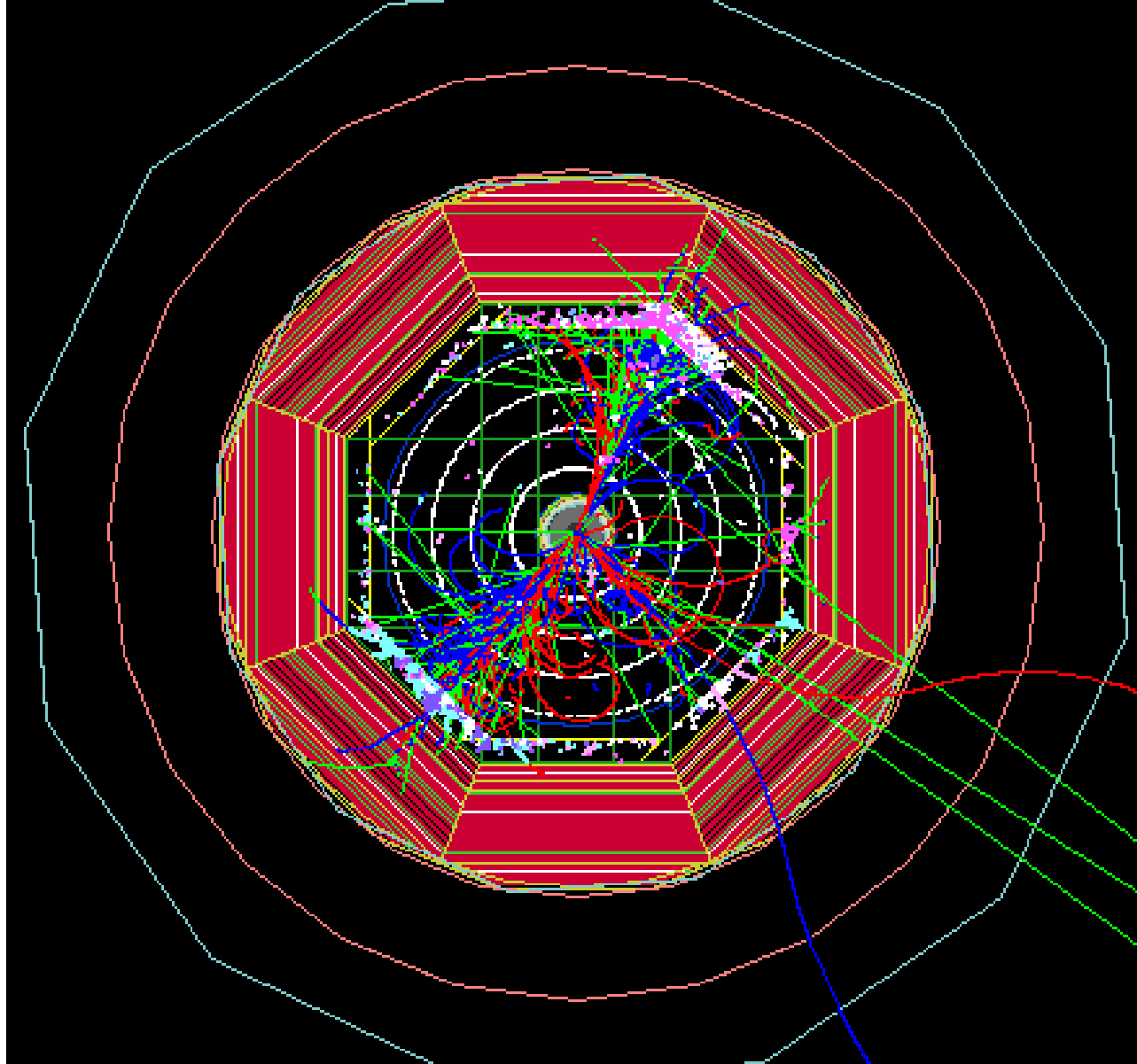
Silicon  
external  
barrel  
component



Silicon  
Internal  
barrel  
component

**$e^+e^- \rightarrow H^\circ \rightarrow t\bar{t} \rightarrow 4q\text{-jets} + 2b\text{-jets}$ ,  $E_{\text{cm}}=750$  GeV  
Pythia +ISR+FSR+beamstrahlung+ full simulation (MOKKA:  
 $\mu\text{vertex}+\text{SIT}+\text{TPC}+\text{SET}+\text{FTD}+\text{Si-FCH}+\text{em calo}+\text{hadron calo}$ )**

**SiD**



**Geant4 simulation of Higgs event in SiD detector, using MOKKA framework including geometry DB for SiD concept**

# What we want to achieve (or at least where we intend to make significant progress on) during the Snowmass Workshop

- Study of the performances of the full tracking system (TPC + Si components) based on GEANT detailed MC simulations and various hypotheses (including reducing TPC volume or not, both in radius and/or length, more realistic estimate of material budget for Si components)
- Comparison between the two detector concepts especially in the Forward region (and possibly progress on XUV CAO design of Si FCH)
- ❖ Need of:
  - >> Informations from the various subdetectors ( $\mu$ vertex, calorimeter, TPC) to properly address the related integration issues
  - >> Feedback from the 2 detector concepts
- ❖ Cooperation of all concerned parties is not only very welcome but strongly needed!